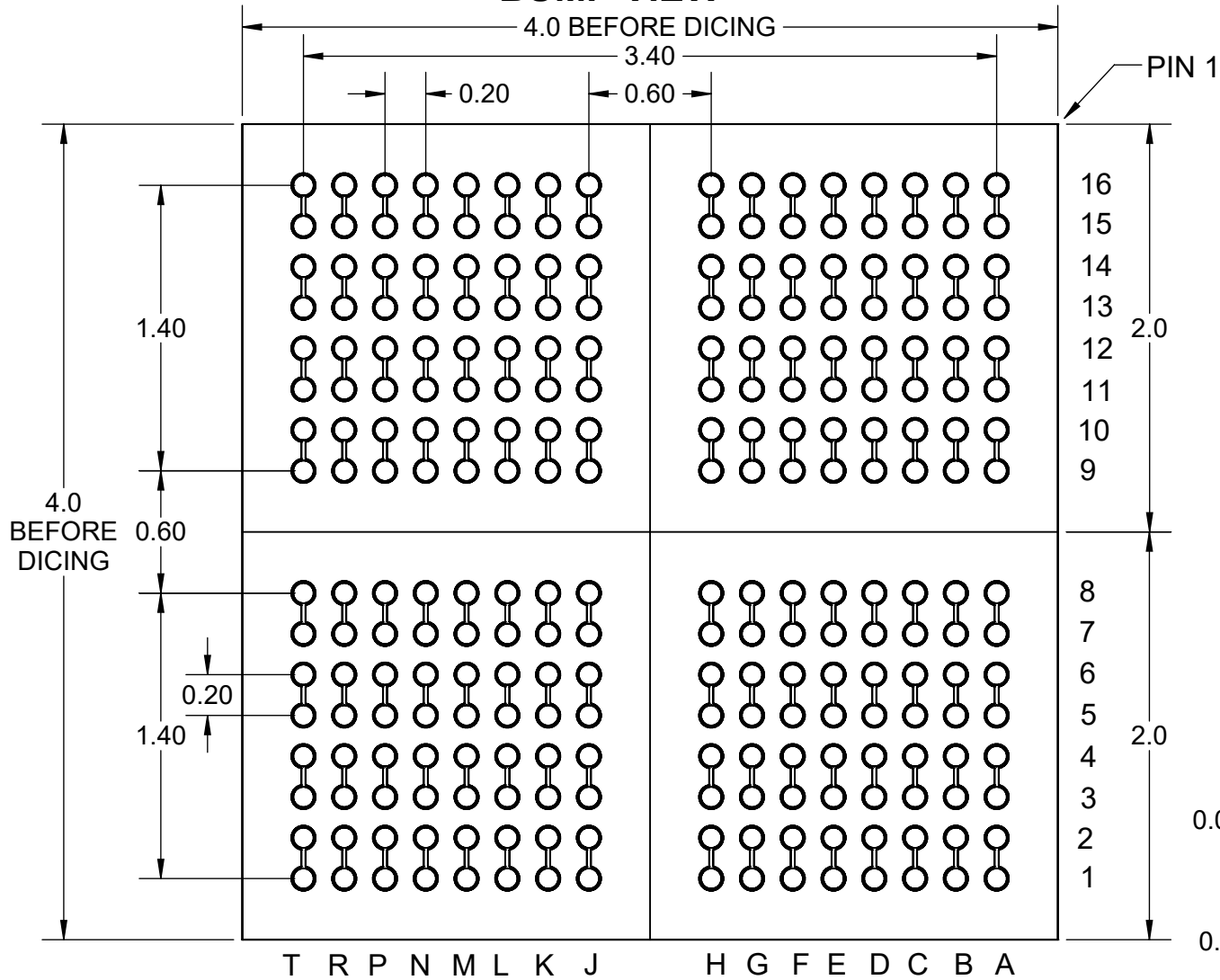
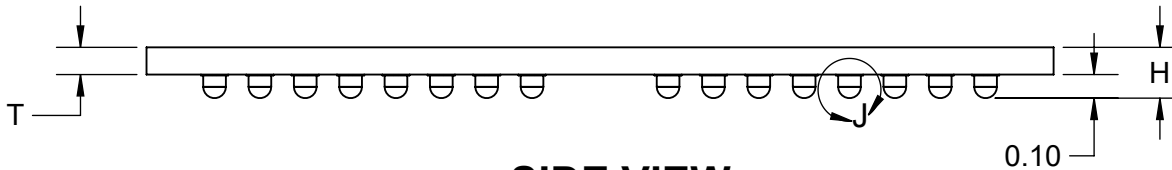
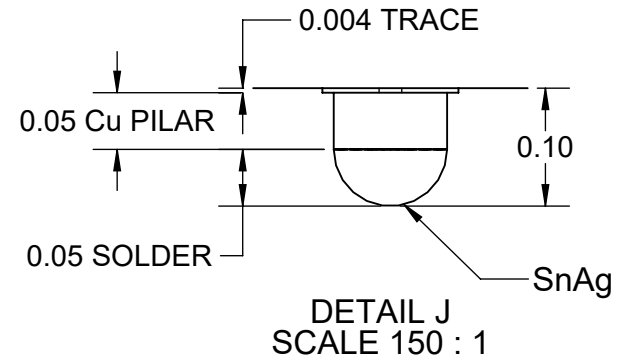


BUMP VIEW



WLP256 PITCH 200um

DIE THICKNESS OPTIONS	
THICKNESS Si DIE (T)	TOTAL THICKNESS WITH BUMPS (H)
0.200mm	0.300mm
0.360mm	0.460mm

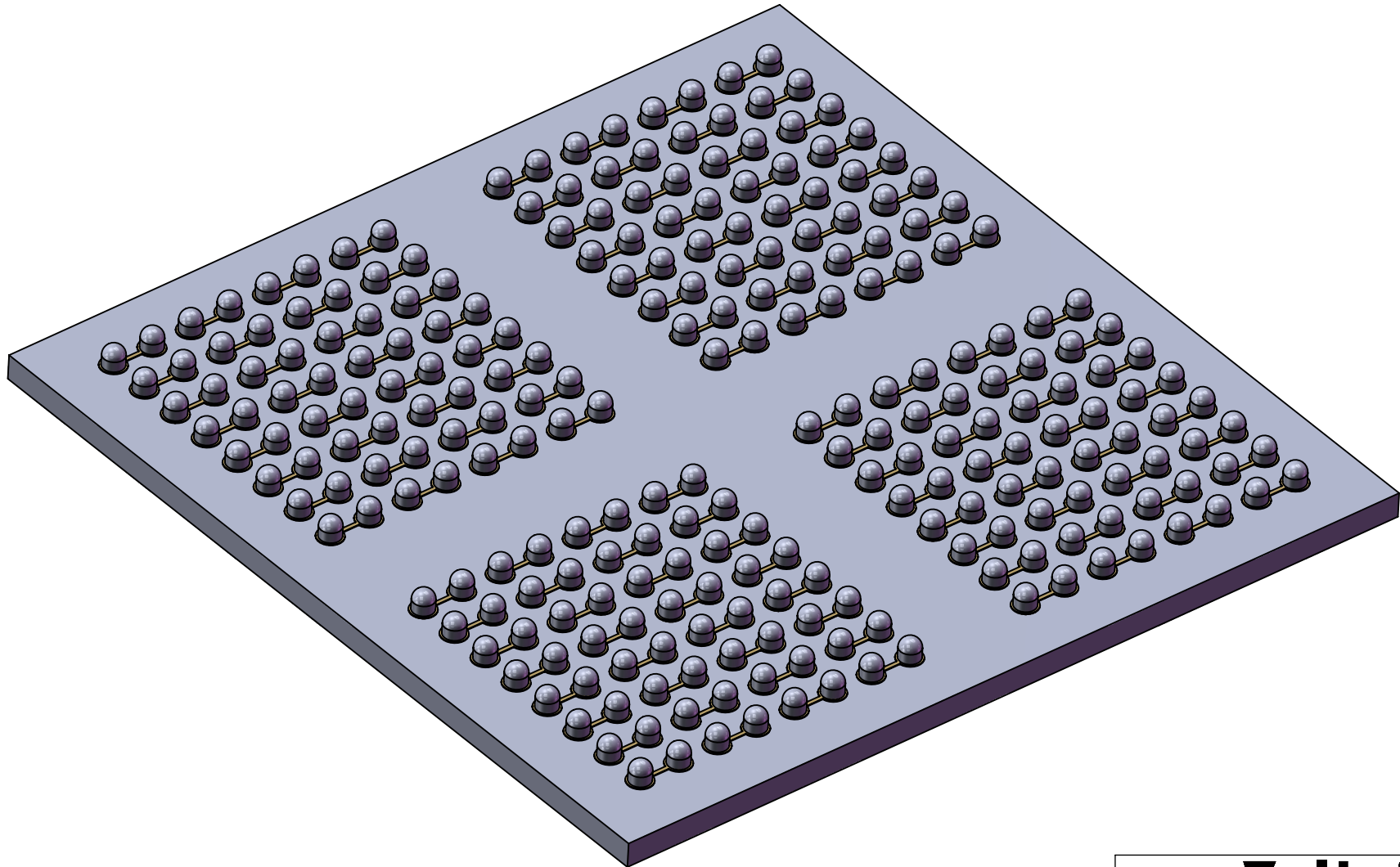


SIDE VIEW Cu PILLAR WITH SOLDER CAP

1. DIMENSIONS MM.

TopLine®			
TITLE WLP256 PITCH 200um DAISY CHAIN 4x4mm			
SCALE 35:1	SIZE A	DRAWING NO. 321682	REV A
DO NOT SCALE DRAWING			SHEET 1 OF 5

MODEL BUMP VIEW



TopLine®

TITLE WLP256 PITCH 200um
DAISY CHAIN 4x4mm

SCALE 35:1	SIZE A	DRAWING NO. 321682	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 5

PART NUMBERING SYSTEM

WLP

256

T

.2

P

- DC168

D

2

SERIES

WLP = WAFER
LEVEL
PRODUCT

NUMBER OF PADS

<u>PADS</u>	<u>SIZE</u>
64	2.0x2.0mm
256	4.0x4.0mm
576	6.0x6.0mm
1024	8.0x8.0mm
1600	10x10mm
2304	12x12mm
3136	14x14mm
4096	16x16mm
999	Full Wafer

PAD PITCH

.2 = 0.2mm
200µm

PACKAGING

<u>CODE</u>	<u>PACKAGE</u>
W =	2" TRAY
T =	4" TRAY
E =	TAPE & REEL
G =	GEL PACK
U =	UV TAPE & RING
X =	UNDICED WAFER

BUMPS

P = Cu Pillar
SnAg Cap

PAD PITCH

DAISY CHAIN DRAWING

DIE THICKNESS

<u>CODE</u>	<u>THICKNESS</u>
2 =	200µm
3 =	360µm

PADS

D = FACE DOWN
U = FACE UP

TopLine®

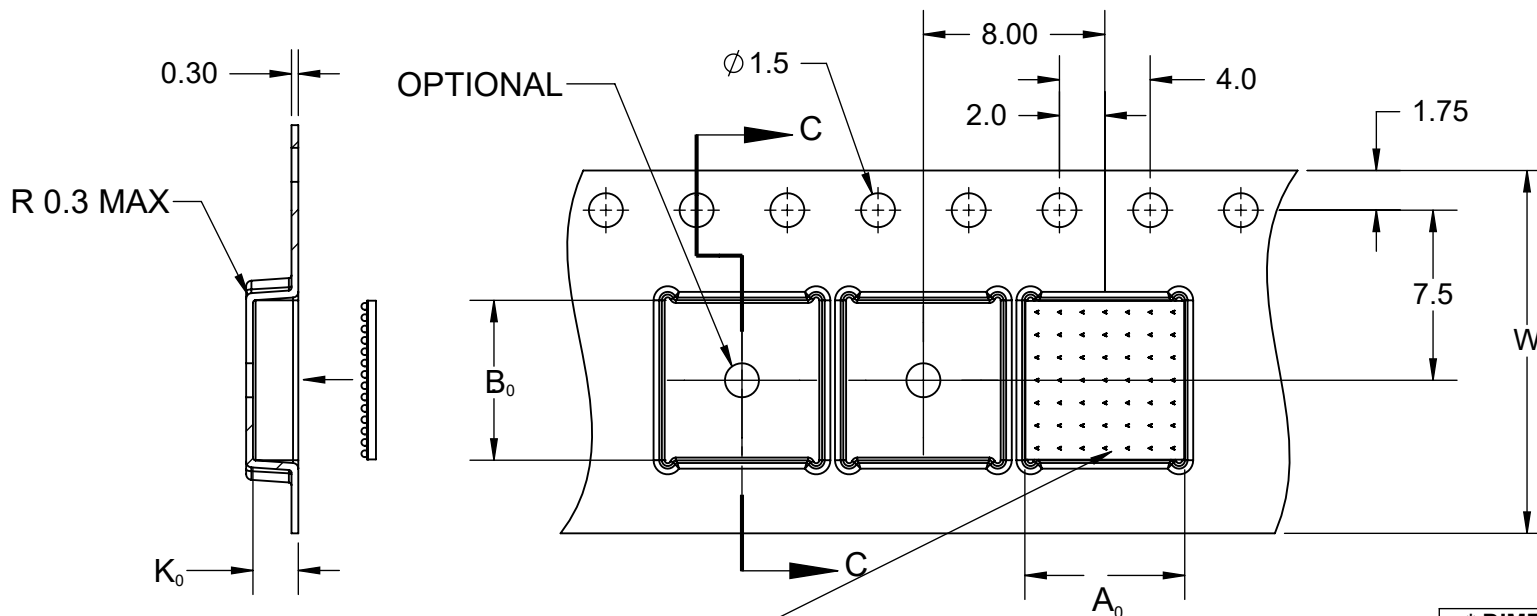
TITLE WLP256 PITCH 200um
DAISY CHAIN 4x4mm

SCALE	SIZE	DRAWING NO.	REV
NONE	A	321682	A

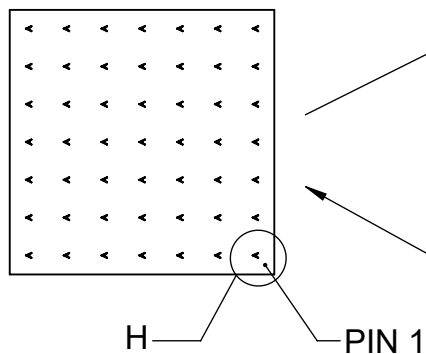
DO NOT SCALE DRAWING

SHEET 3 OF 5

EXAMPLE OF CARRIER TYPE

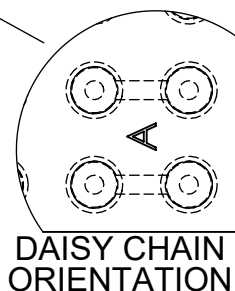


SECTION C-C
SCALE 3 : 1



* MARKING CODE	
PITCH	LETTER
0.2MM	M
0.3MM	A
0.35MM	Y
0.4MM	F
0.5MM	P

* SUBJECT TO CHANGE



DETAIL H
SCALE 25 : 1

* DIMENSION TABLE (MM)	
A ₀ =	~ 4.4
B ₀ =	~ 4.4
K ₀ =	1.0 ~ 2.0
W =	12 ~ 16

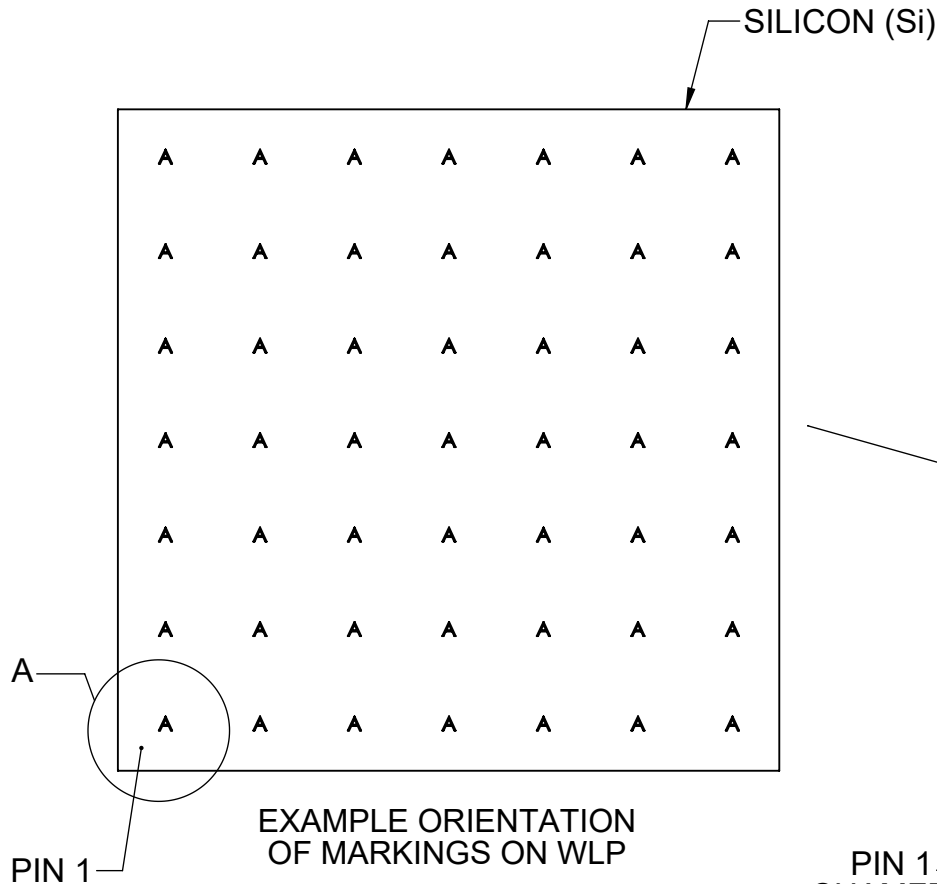
* TAPE DIMENSION SUBJECT TO CHANGE

Notes: (Unless Otherwise Specified).

- 1) CARRIER TAPE SHOWN AS EXAMPLE ONLY. ACTUAL TAPE DIMENSIONS ARE DEPENDENT ON X/Y/Z SIZE OF WLP.
- 2) SURFACE OF WLP IS MARKED WITH SINGLE LETTER REPEATED MULTIPLE TIMES ACROSS TOP SURFACE.
- 3) LETTERS INDICATE ORIENTATION OF PIN A1.
- 4) 200μm THIN DIE ARE UNMARKED.

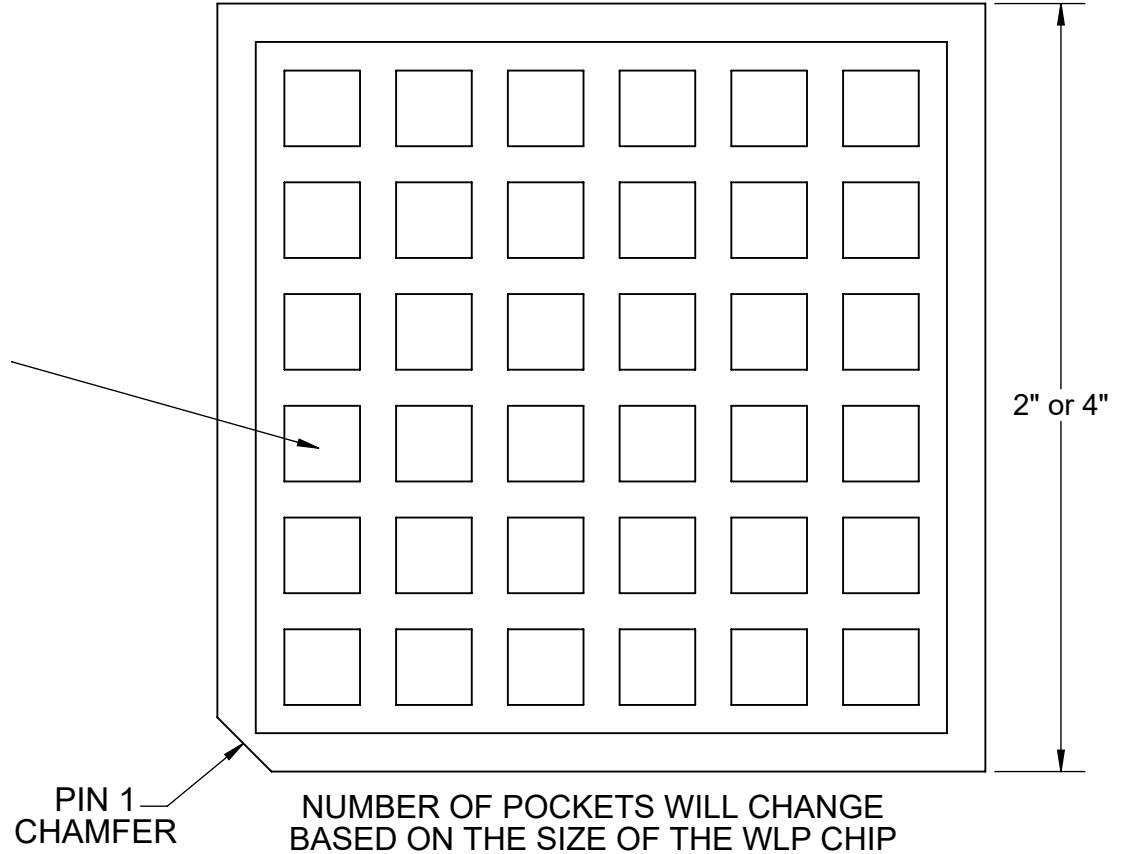
TITLE		WLP ORIENTATION TAPE AND REEL	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	321682	A
DO NOT SCALE DRAWING			SHEET 4 OF 5

TOP VIEW



EXAMPLE ORIENTATION OF MARKINGS ON WLP

TYPICAL WAFFLE PACK IC CHIP TRAY
SCALE = 2:1

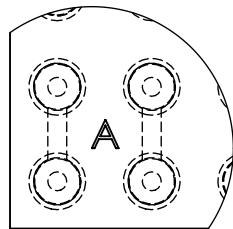


Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) 200µm THIN DIE ARE UNMARKED.

* MARKING CODE	
PITCH	LETTER
0.2MM	M
0.3MM	A
0.35MM	Y
0.4MM	F
0.5MM	P

* SUBJECT TO CHANGE



DAISY CHAIN ORIENTATION

DETAIL A
SCALE 25 : 1

TopLine®

TITLE		WLP ORIENTATION WAFFLE PACK	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	504019	A
DO NOT SCALE DRAWING		SHEET 5 OF 5	